

Global Wire Wedge Bonder Equipment Market Data Survey Report 2025

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Abstracts

Summary

Wedge bonding can be a great solution for performing low profile or fine pitch interconnects and is also well suited for running stitch interconnects (also known as die-to-die bonding and chain bonding), reverse bonding, and ribbon bonding.

The global Wire Wedge Bonder Equipment market will reach Volume Million USD in 2017 with CAGR xx% 2018-2025. The main contents of the report including:

Global market size and forecast

Regional market size, production data and export & import

Key manufacturers (manufacturing sites, capacity and production, product specifications etc.)

Average market price by SUK

Major applications

Key manufacturers are included based on manufacturing sites, capacity and production, product specifications etc.:

Kulicke & Soffa

ASM Pacific Technology (ASMPT)

Hesse

Cho-Onpa

F&K Delvotec Bondtechnik

Palomar Technologies

DIAS Automation

West-Bond

Hybond

TPT

Major applications
as follows:

Integrated Device Manufacturers (IDMs)

Outsourced Semiconductor Assembly and Test (OSAT)

Regional market size, production data and export & import:

Asia-Pacific

North America

Europe

South America

Middle East & Africa

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